# TPS65912x Errata

This document describes the TPS65912x bugs, limitations, and enhancements with suggested workarounds. As this information is dated, updates will be provided.

# 1 High Iq Due to a Floating Node

**Impact:**

The TPS65912x family devices may experience higher Iq (only when VCC is powered and VDDIO is not) due to a floating node on GPIO1 level shifters. The high Iq can also be observed if the device is in the off state and the VDDIO is supplied by one of the TPS65912x outputs; here, VCC is powered and VDDIO is not. A recommended use case is to have the TPS65912x output supply VDDIO (see the *Applications, Implementation, and Layout* section of SWCS071).

**Description:**

The nominal Iq is around 30 µA, but the high Iq can be as high as 150 µA. However, if the device shows the high Iq, it is likely to be about 90 µA. Not all devices show this behavior, and not all devices show the same behavior (as compared to themselves) across temperature.

**Workaround:**

To eliminate this extra Iq, supply VDDIO with an always-on source either externally or by using LDOA2 from the device. Using LDOA2 as the source would limit the voltage available for running the I/O of the device to the voltage of LDOA2.

## 2 Revision History

| Version | Date | Notes |
|---|---|---|
| * | April 2015 | Initial release |

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